Transfer Fabrication Technique for Embedded and Inverted Micro/Nanostructures

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A transfer fabrication technique is developed to construct embedded and inverted micro/nanostructures that cannot be readily built by other methods. Transfer patterning/printing is used for the fabrication, which involves transferring a patterned layer on a flat substrate to another substrate that has a higher work of adhesion with the layer than the flat substrate. The technique is relatively simple and fast (~10 s). Inversion of a shape that is made possible by the transfer is the basic concept. This inversion allows fabrication of three–dimensional embedded structures through multiple stacking. The technique could open new avenues for various applications.